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#### FAIRCHILD

SEMICONDUCTOR

#### SCAN18374T **D-Type Flip-Flop with 3-STATE Outputs**

#### **General Description**

The SCAN18374T is a high speed, low-power D-type flipflop featuring separate D-type inputs organized into dual 9bit bytes with byte-oriented clock and output enable control signals. This device is compliant with IEEE 1149.1 Standard Test Access Port and BOUNDARY-SCAN Architecture with the incorporation of the defined BOUNDARY-SCAN test logic and test access port consisting of Test Data Input (TDI), Test Data Out (TDO), Test Mode Select (TMS), and Test Clock (TCK).

#### **Features**

- IEEE 1149.1 (JTAG) Compliant
- Buffered positive edge-triggered clock
- 3-STATE outputs for bus-oriented applications
- 9-bit data busses for parity applications
- Reduced-swing outputs source 32 mA/sink 64 mA
- Guaranteed to drive 50Ω transmission line to TTL input levels of 0.8V and 2.0V
- TTL compatible inputs
- 25 mil pitch SSOP (Shrink Small Outline Package)
- Includes CLAMP and HIGHZ instructions
- Member of Fairchild's SCAN Products

#### **Ordering Code:**

Order Number	Package Number	Package Description					
SCAN18374TSSC	MS56A	56-Lead Shrink Small Outline Package (SSOP), JEDEC MO-118, 0.300 Wide					
Devices also available i	Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.						

#### **Connection Diagram**

Pin	Desc	crip	tio	ns
	2000	p		

Pin Names	Description
AI <sub>(0-8)</sub> , BI <sub>(0-8)</sub> ACP, BCP	Data Inputs
ACP, BCP	Clock Pulse Inputs
$\overline{AOE}_1, \overline{BOE}_1$	3-STATE Output Enable Inputs
AO <sub>(0-8)</sub> , BO <sub>(0-8)</sub>	3-STATE Outputs

#### **Truth Tables**

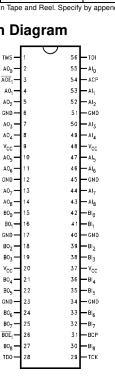
	Inputs		40
ACP	AOE <sub>1</sub>	AI <sub>(0-8)</sub>	AO <sub>(0-8)</sub>
Х	Н	Х	Z
~	L	L	L
, ,	L	Н	Н
	Inputs		BO
ВСР	Inputs BOE <sub>1</sub>	BI <sub>(0-8)</sub>	BO <sub>(0-8)</sub>
BCP X		ВІ <sub>(0–8)</sub> Х	BO <sub>(0-8)</sub> Z
	BOE <sub>1</sub>		
	BOE <sub>1</sub>		

L = LOW Voltage Level

X = Immaterial

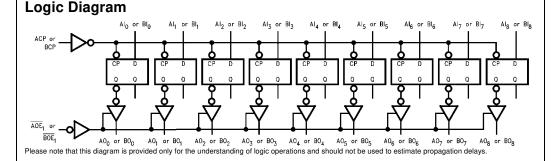
= L-to-H Transition

- Z = High Impedance

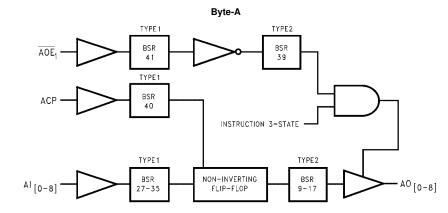


#### **Functional Description**

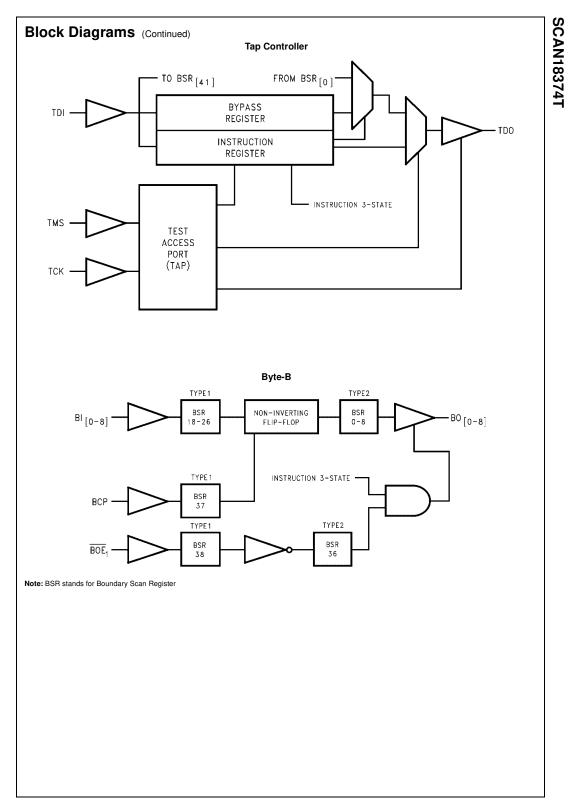
The SCAN18374 consists of two sets of nine edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The buffered clock and buffered Output Enable pins are common to all flip-flops. Each set of the nine flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (ACP or BCP) transition. With the Output Enable ( $\overline{AOE}_1$  or  $\overline{BOE}_1$ ) LOW, the contents of the nine flip-flops are available at the outputs. When the Output Enable is HIGH, the outputs go to the high impedance state. Operation of the Output Enable input does not affect the state of the flip-flops.



#### **Block Diagrams**



Note: BSR stands for Boundary Scan Register

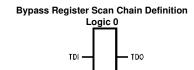


#### **Description of Boundary-Scan Circuitry**

The scan cells used in the BOUNDARY-SCAN register are one of the following two types depending upon their location. Scan cell TYPE1 is intended to solely observe system data, while TYPE2 has the additional ability to control system data.

Scan cell TYPE1 is located on each system input pin while scan cell TYPE2 is located at each system output pin as well as at each of the two internal active-high output enable signals. AOE controls the activity of the A-outputs while BOE controls the activity of the B-outputs. Each will activate their respective outputs by loading a logic high.

The BYPASS register is a single bit shift register stage identical to scan cell TYPE1. It captures a fixed logic low.



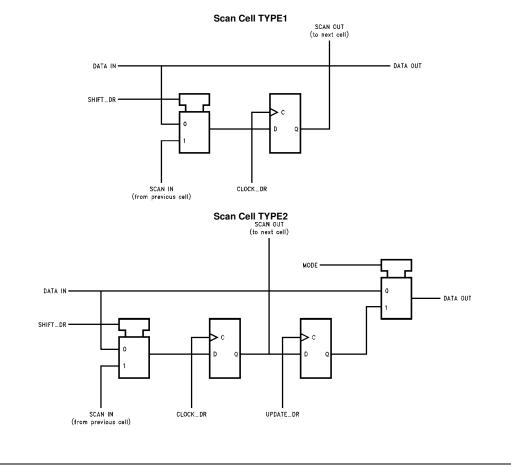
The INSTRUCTION register is an eight-bit register which captures the value 00111101.

The two least significant bits of this captured value (01) are required by IEEE Std 1149.1. The upper six bits are unique to the SCAN18374T device. SCAN CMOS Test Access Logic devices do not include the IEEE 1149.1 optional identification register. Therefore, this unique captured value can be used as a "pseudo ID" code to confirm that the correct device is placed in the appropriate location in the boundary scan chain.



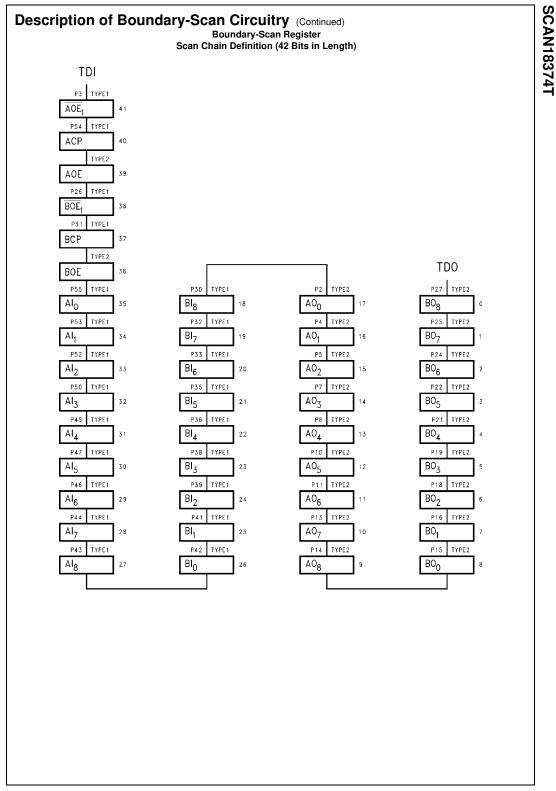
 $MSB \rightarrow LSB$ 

Instruction Code	Instruction
0000000	EXTEST
1000001	SAMPLE/PRELOAD
10000010	CLAMP
00000011	HIGHZ
All Others	BYPASS



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41			Pin Type	Scan Cell Type		
	AOE <sub>1</sub>	3	Input	TYPE1	Contro	
40	ACP	54	Input	TYPE1	Signal	
39	AOE		Internal	TYPE2		
38	BOE <sub>1</sub>	26	Input	TYPE1		
37	BCP	31	Input	TYPE1		
36	BOE		Internal	TYPE2		
35	Al <sub>0</sub>	55	Input	TYPE1	A–in	
34	Al <sub>1</sub>	53	Input	TYPE1		
33	Al <sub>2</sub>	52	Input	TYPE1		
32	Al <sub>3</sub>	50	Input	TYPE1		
31	Al <sub>4</sub>	49	Input	TYPE1		
30	AI <sub>5</sub>	47	Input	TYPE1		
29	Al <sub>6</sub>	46	Input	TYPE1		
28	AI <sub>7</sub>	44	Input	TYPE1		
27	Al <sub>8</sub>	43	Input	TYPE1		
26	BI0	42	Input	TYPE1	B–in	
25	BI <sub>1</sub>	41	Input	TYPE1		
24	BI <sub>2</sub>	39	Input	TYPE1		
23	BI3	38	Input	TYPE1		
22	BI <sub>4</sub>	36	Input	TYPE1		
21	BI <sub>5</sub>	35	Input	TYPE1		
20	BI <sub>6</sub>	33	Input	TYPE1		
19	BI <sub>7</sub>	32	Input	TYPE1		
18	BI <sub>8</sub>	30	Input	TYPE1		
17	AO <sub>0</sub>	2	Output	TYPE2	A–ou	
16	AO <sub>1</sub>	4	Output	TYPE2		
15	AO <sub>2</sub>	5	Output	TYPE2		
14	AO <sub>3</sub>	7	Output	TYPE2		
13	AO <sub>4</sub>	8	Output	TYPE2		
12	AO <sub>5</sub>	10	Output	TYPE2		
11	AO <sub>6</sub>	11	Output	TYPE2		
10	AO <sub>7</sub>	13	Output	TYPE2		
9	AO <sub>8</sub>	14	Output	TYPE2		
8	BO <sub>0</sub>	15	Output	TYPE2	B–ou	
7	BO <sub>1</sub>	16	Output	TYPE2		
6	BO <sub>2</sub>	18	Output	TYPE2		
5	BO3	19	Output	TYPE2		
4	BO <sub>4</sub>	21	Output	TYPE2		
3	BO <sub>5</sub>	22	Output	TYPE2		
2	BO <sub>6</sub>	24	Output	TYPE2		
1	BO <sub>7</sub>	25	Output	TYPE2		
0	BO <sub>8</sub>	27	Output	TYPE2		

#### Absolute Maximum Ratings(Note 1)

	-
Supply Voltage (V <sub>CC</sub> )	-0.5V to +7.0V
DC Input Diode Current (IIK)	
$V_{I} = -0.5V$	-20 mA
$V_I = V_{CC} + 0.5V$	+20 mA
DC Output Diode Current (I <sub>OK</sub> )	
$V_{O} = -0.5V$	–20 mA
$V_O = V_{CC} + 0.5V$	+20 mA
DC Output Voltage (V <sub>O</sub> )	–0.5V to V <sub>CC</sub> +0.5V
DC Output Source/Sink Current (I <sub>O</sub> )	±70 mA
DC V <sub>CC</sub> or Ground Current	
Per Output Pin	±70 mA
Junction Temperature	
SSOP	+140°C
Storage Temperature	-65°C to +150°C
ESD (Min)	2000V

### Recommended Operating Conditions

Supply Voltage (V <sub>CC</sub> )	
SCAN Products	4.5V to 5.5V
Input Voltage (VI)	0V to $V_{CC}$
Output Voltage (V <sub>O</sub> )	0V to $V_{CC}$
Operating Temperature (T <sub>A</sub> )	$-40^{\circ}C$ to $+85^{\circ}C$
Minimum Input Edge Rate $\Delta V/\Delta t$	125 mV/ns
V <sub>IN</sub> from 0.8V to 2.0V	
V <sub>CC</sub> @ 4.5V, 5.5V	

Note 1: Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation of SCAN circuits outside databook specifications.

#### **DC Electrical Characteristics**

Symbol	Parameter	$V_{CC}$ $T_A = +25^{\circ}C$		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	Units	O an dition o	
Symbol	Parameter	(V)	Typ Gua		aranteed Limits	Units	Conditions
/ <sub>IH</sub>	Minimum HIGH	4.5	1.5	2.0	2.0	V	V <sub>OUT</sub> = 0.1V
	Input Voltage	5.5	1.5	2.0	2.0	v	or V <sub>CC</sub> –0.1V
V <sub>IL</sub>	Maximum LOW	4.5	1.5	0.8	0.8	V	V <sub>OUT</sub> = 0.1V
	Input Voltage	5.5	1.5	0.8	0.8	v	or V <sub>CC</sub> –0.1V
V <sub>OH</sub>	Minimum HIGH	4.5		3.15	3.15	V	
	Output Voltage	5.5		4.15	4.15	v	$I_{OUT} = -50 \ \mu A$
	(Note 2)	4.5		2.4	2.4	V	$V_{IN} = V_{IL} \text{ or } V_{IH}$
		5.5		2.4	2.4	v	$I_{OH} = -32 \text{ mA}$
		4.5		2.4		v	$V_{IN} = V_{IL} \text{ or } V_{IH}$
		5.5		2.4		v	$I_{OH} = -24 \text{ mA}$
V <sub>OL</sub>	Maximum LOW	4.5		0.1	0.1	V	L 50 ··· A
	Output Voltage	5.5		0.1	0.1	v	$I_{OUT} = 50 \ \mu A$
	(Note 2)	4.5		0.55	0.55	V	$V_{IN} = V_{IL} \text{ or } V_{IH}$
		5.5		0.55	0.55	v	$I_{OL} = 64 \text{ mA}$
		4.5		0.55		V	$V_{IN} = V_{IL} \text{ or } V_{IH}$
		5.5		0.55		v	I <sub>OL</sub> = 48 mA
I <sub>IN</sub>	Maximum Input			10.4	11.0		V V 0ND
	Leakage Current	5.5		±0.1	±1.0	μA	$V_I = V_{CC},  GND$
IN	Maximum Input	5.5		2.8	3.6	μA	$V_I = V_{CC}$
TDI, TMS	Leakage			-385	-385	μA	$V_I = GND$
	Minimum Input Leakage	5.5		-160	-160	μA	$V_I = GND$
OLD	Minimum Dynamic	5.5		94	94	mA	V <sub>OLD</sub> = 0.8V Max
I <sub>OHD</sub>	Output Current (Note 3)			-40	-40	mA	$V_{OHD} = 2.0V$ Min
oz	Maximum Output	5.5		±0.5	±5.0		$V_{I}$ (OE) = $V_{II}$ , $V_{IH}$
	Leakage Current	5.5		±0.5	±5.0	μA	$v_{I}(OE) = v_{IL}, v_{IH}$
os	Output Short	5.5		-100	-100	mA	$V_{O} = 0V$
	Circuit Current					(min)	
сс	Maximum Quiescent	5.5		16.0	88		V <sub>O</sub> = Open
	Supply Current	5.5		10.0	00	μA	TDI, TMS = $V_{CC}$
		E		750	820		V <sub>O</sub> = Open
		5.5		750	820	μA	TDI, TMS = GND

# SCAN18374T

## SCAN18374T

#### DC Electrical Characteristics (Continued)

Symbol	Parameter	v <sub>cc</sub>	T <sub>A</sub> = +25°C		$\textbf{T}_{\textbf{A}} = -40^{\circ}\textbf{C} \text{ to } +85^{\circ}\textbf{C}$	Units	Conditions	
Cymbol		(V)	Тур	Guaranteed Limits		onito		
I <sub>CCt</sub>	Maximum I <sub>CC</sub>	5.5		2.0	2.0	mA	$V_{I} = V_{CC} - 2.1V$	
	Per Input	5.5		2.15	2.15	mA	$V_I = V_{CC} - 2.1V$ TDI/TMS Pin, Test One with the Other Floating	

Note 2: All outputs loaded; thresholds associated with output under test. Note 3: Maximum test duration 2.0 ms, one output loaded at a time.

#### **Noise Specifications**

Symbol	Parameter	V <sub>cc</sub>	T <sub>A</sub> = +25°C		$T_A = -40^{\circ}C$ to $+85^{\circ}C$	Units
Symbol	i arameter	(V)	Typ Gu		ranteed Limits	
V <sub>OLP</sub>	Maximum HIGH Output Noise	5.0	1.0	1.5		v
	(Note 5)(Note 6)	0.0				•
V <sub>OLV</sub>	Minimum LOW Output Noise	5.0	-0.6	-1.2		v
	(Note 5)(Note 6)	5.0	-0.0	-1.2		v
V <sub>OHP</sub>	Maximum Overshoot	5.0	V <sub>ОН</sub> +1.0	V <sub>ОН</sub> +1.5		v
	(Note 4)(Note 6)	5.0	VOH-1.0	*0H11.0		•
V <sub>OHV</sub>	Minimum V <sub>CC</sub> Droop	5.0	V <sub>OH</sub> -1.0	V <sub>ОН</sub> −1.8		v
	(Note 4)(Note 6)	5.0	•OH-1.0	•OH-1.0		v
V <sub>IHD</sub>	Minimum HIGH Dynamic Input Voltage Level	5.5	1.6	2.0	2.0	v
	(Note 4)(Note 7)	5.5	1.0	2.0	2.0	v
V <sub>ILD</sub>	Maximum LOW Dynamic Input Voltage Level	5.5	1.4	0.8	0.8	v
	(Note 4)(Note 7)	5.5	1.4	0.0	0.0	v

Note 4: Worst case package.

Note 5: Maximum number of outputs that can switch simultaneously is n. (n-1) outputs are switched LOW and one output held LOW. Note 6: Maximum number of outputs that can switch simultaneously is n. (n - 1) outputs are switched HIGH and one output held HIGH. Note 7: Maximum number of data inputs (n) switching. (n - 1) input switching 0V to 3V. Input under test switching 3V to threshold (V<sub>ILD</sub>).

#### **AC Electrical Characteristics**

Symbol	Parameter	V <sub>CC</sub> (V)		$T_A = +25^{\circ}C$ $C_L = 50 \text{ pF}$			C to +85°C 50 pF	Units
		(Note 8)	Min	Тур	Max	Min	Max	
t <sub>PLH</sub> ,	Propagation Delay	5.0	2.5		9.5	2.5	10.5	
t <sub>PHL</sub>	CP to Q		2.5		10.3	2.5	11.5	ns
t <sub>PLZ</sub> ,	Disable Time	5.0	1.5		9.0	1.5	9.5	20
t <sub>PHZ</sub>			1.5		9.0	1.5	10.0	ns
t <sub>PZL</sub> ,	Enable Time	5.0	2.0		10.9	2.0	12.0	
t <sub>PZH</sub>			2.0		8.9	2.0	9.5	ns

Note 8: Voltage Range 5.0 is  $5.0V \pm 0.5V$ .

#### **AC Operating Requirements**

Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ $C_L = 50 \text{ pF}$	Units
		(Note 9)	Guarant		
s	Setup Time, H or L	5.0	3.0	3.0	ns
	Data to CP	5.0	3.0	3.0	115
t <sub>H</sub>	Hold Time, H or L	5.0	1.5	1.5	ns
	CP to Data	5.0		1.5	115
w	CP Pulse Width	5.0	5.0	5.0	ns
MAX	Maximum ACP/BCP Clock Frequency	5.0	100	90	MHz

Scan Test	Operation			-				
		V <sub>cc</sub>	T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF				C to +85°C	
Symbol	Parameter	(V)				$C_L = 50 \text{ pF}$		Units
		(Note 10)	Min	Тур	Max	Min	Max	
t <sub>PLH</sub> ,	Propagation Delay	5.0	3.5		13.2	3.5	14.5	ns
t <sub>PHL</sub>	TCK to TDO		3.5		13.2	3.5	14.5	113
t <sub>PLZ</sub> ,	Disable Time	5.0	2.5		11.5	2.5	11.9	ns
t <sub>PHZ</sub>	TCK to TDO		2.5		11.5	2.5	11.9	113
t <sub>PZL</sub> ,	Enable Time	5.0	3.0		14.5	3.0	15.8	ns
t <sub>PZH</sub>	TCK to TDO		3.0		14.5	3.0	15.8	115
t <sub>PLH</sub> ,	Propagation Delay	5.0	5.0		18.0	5.0	19.8	
t <sub>PHL</sub>	TCK to Data Out		5.0		18.0	5.0	19.8	ns
	During Update-DR State							
t <sub>PLH</sub> ,	Propagation Delay	5.0	5.0		18.6	5.0	20.2	
t <sub>PHL</sub>	TCK to Data Out		5.0		18.6	5.0	20.2	ns
	During Update-IR State							
t <sub>PLH</sub> ,	Propagation Delay	5.0	5.5		19.9	5.5	21.5	
t <sub>PHL</sub>	TCK to Data Out		5.5		19.9	5.5	21.5	ns
	During Test Logic Reset State							
t <sub>PLZ</sub> ,	Propagation Delay	5.0	4.0		16.4	4.0	18.2	
t <sub>PHZ</sub>	TCK to Data Out		4.0		16.4	4.0	18.2	ns
	During Update-DR State							
t <sub>PLZ</sub> ,	Propagation Delay	5.0	5.0		19.5	5.0	20.8	
t <sub>PHZ</sub>	TCK to Data Out		5.0		19.5	5.0	20.8	ns
	During Update-IR State							
t <sub>PLZ</sub> ,	Propagation Delay	5.0	5.0		19.9	5.0	21.5	
t <sub>PHZ</sub>	TCK to Data Out		5.0		19.9	5.0	21.5	ns
	During Test Logic Reset State							
t <sub>PZL</sub> ,	Propagation Delay	5.0	5.0		18.9	5.0	20.9	
t <sub>PZH</sub>	TCK to Data Out		5.0		18.9	5.0	20.9	ns
	During Update-DR State							
t <sub>PZL</sub> ,	Propagation Delay	5.0	6.5		22.4	6.5	24.2	
t <sub>PZH</sub>	TCK to Data Out		6.5		22.4	6.5	24.2	ns
	During Update-IR State							
t <sub>PZL</sub> ,	Propagation Delay	5.0	7.0		23.8	7.0	25.7	
t <sub>PZH</sub>	TCK to Data Out		7.0		23.8	7.0	25.7	ns
1 211	During Test Logic Reset State					-	-	

Note 10: Voltage Range 5.0 is  $5.0V \pm 0.5V$ .

Note: All Propagation Delays involving TCK are measured from the falling edge of TCK.

SCAN18374T

#### **AC Operating Requirements**

Scan Test Operation

		V <sub>CC</sub>	$T_A = +25^{\circ}C$	$T_{A}=-40^{\circ}C$ to $+85^{\circ}C$	
Symbol	Parameter	(V)	$C_L = 50 \text{ pF}$	$C_L = 50 \text{ pF}$	Units
		(Note 11)	Guaranteed Minimum		
t <sub>S</sub>	Setup Time, H or L	5.0	3.0	2.0	20
	Data to TCK (Note 12)	5.0	3.0	3.0	ns
t <sub>H</sub>	Hold Time, H or L	5.0	4.5	4.5	
	TCK to Data (Note 12)	5.0	4.5	4.0	ns
t <sub>S</sub>	Setup Time, H or L	5.0	3.0	3.0	ns
-	AOE <sub>1</sub> , BOE <sub>1</sub> to TCK (Note 13)	5.0	5.0	5.0	115
t <sub>H</sub>	Hold Time, H or L	5.0	4.5	4.5	ns
	TCK to $\overline{AOE_1}$ , $\overline{BOE_1}$ (Note 13)	5.0	4.5	4.5	113
t <sub>S</sub>	Setup Time, H or L	5.0	3.0	3.0	ns
	Internal AOE, BOE to TCK (Note 14)	0.0	0.0	0.0	110
t <sub>H</sub>	Hold Time, H or L	5.0	3.0	3.0	ns
	TCK to Internal AOE, BOE (Note 14)				
t <sub>S</sub>	Setup Time	5.0	3.0	3.0	ns
	ACP, BCP (Note 15) to TCK				
t <sub>H</sub>	Hold Time	5.0	3.5	3.5	ns
	TCK to ACP, BCP (Note 15)				-
t <sub>S</sub>	Setup Time, H or L	5.0	8.0	8.0	ns
	TMS to TCK				
t <sub>H</sub>	Hold Time, H or L	5.0	2.0	2.0	ns
	TCK to TMS				
t <sub>S</sub>	Setup Time, H or L	5.0	4.0	4.0	ns
	TDI to TCK				
t <sub>H</sub>	Hold Time, H or L	5.0	4.5	4.5	ns
	TCK to TDI	5.0			
t <sub>W</sub>	Pulse Width TCK	5.0	15.0	15.0	
	н		15.0	15.0	ns
,	L		5.0	5.0	
f <sub>MAX</sub>	Maximum TCK	5.0	25	25	MHz
Ŧ	Clock Frequency	5.0	100	100	
T <sub>pu</sub>	Wait Time, Power Up to TCK	5.0	100	100	ns
T <sub>dn</sub>	Power Down Delay	0.0	100	100	ms

Note 11: Voltage Range 5.0 is  $5.0V \pm 0.5V$ .

Note 12: This delay represents the timing relationship between the data Input and TCK at the associated scan cells numbered 0-8, 9-17, 18-26 and 27-35. Note 13: Timing pertains to BSR 38 and 41 only.

Note 14: This delay represents the timing relationship between AOE, BOE and TCK at scan cells 36 and 39 only.

Note 15: Timing pertains to BSR 37 and 40 only.

Note: All Input Timing Delays involving TCK are measured from the rising edge of TCK.

Symbol	Parameter		$T_{A} = +25^{\circ}C$ $V_{CC} = 5.0V$ $C_{L} = 50 \text{ pF}$ 18 Outputs Switching (Note 16)			$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $V_{CC} = 5.0V \pm 0.5V$ $C_{L} = 250 \text{ pF}$ (Note 17)	
		Min	Тур	Max	Min	Max	
t <sub>PLH</sub> ,	Propagation Delay	3.0		11.5	4.0	13.5	ns
t <sub>PHL</sub>	Data to Output	3.0		12.5	4.0	16.5	ns
t <sub>PZH</sub> ,	Output Enable Time	2.5		10.5	(Note 18)		20
t <sub>PZL</sub>				2.5			ns
t <sub>PHZ</sub> ,	Output Disable Time	2.0		10.5	(Note 19)		ns
t <sub>PLZ</sub>		2.0		10.5			
toshl	Pin to Pin Skew		0.5	1.0		1.0	
(Note 20)	HL Data to Output						ns
tOSLH	Pin to Pin Skew		0.5	1.0		1.0	ns
(Note 20)	LH Data to Output						IIS

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Note 16: This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.).

Note 17: This specification is guaranteed but not tested. The limits represent propagation delays with 250 pF load capacitors in place of the 50 pF load capacitors in the standard AC load. This specification pertains to single output switching only.

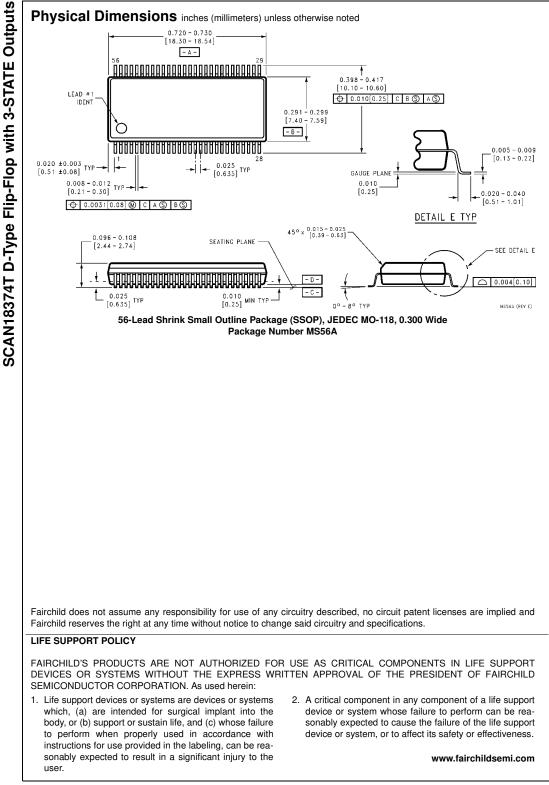
Note 18: 3-STATE delays are load dominated and have been excluded from the datasheet.

Note 19: The Output Disable Time is dominated by the RC network (500Ω, 250 pF) on the output and has been excluded from the datasheet.

Note 20: Skew is defined as the absolute value of the difference between the actual propagation delays for any two separate outputs of the same device. The specification applies to any outputs switching HIGH-to-LOW (t<sub>OSHL</sub>), LOW-to-HIGH (t<sub>OSLH</sub>), or any combination switching LOW-to-HIGH and/or HIGH-to-LOW.

#### Capacitance

Symbol	Parameter	Тур	Units	Conditions
CIN	Input Pin Capacitance	4.0	pF	$V_{CC} = 5.0V$
C <sub>OUT</sub>	Output Pin Capacitance	13.0	pF	$V_{CC} = 5.0V$
C <sub>PD</sub>	Power Dissipation Capacitance	34.0	pF	$V_{CC} = 5.0V$



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